

IN THE CLAIMS:

Please enter any changes in the claims indicated in the complete copy of the pending claims, as sought to be amended, presented below:

1-11. **(Canceled).**

12. **(Currently Amended)** A method of forming transmission lines and openings for buried passive components in green tapes comprising

embossing a channel directly on the surface of a green tape using heat and pressure sufficient to transfer the pattern from the embossing tool to the green tape,

screen printing conductive ink into the channel and covering by the steps consisting essentially of:

i. screen printing a suitable said ink into the channel, and directly onto the surface of the green tape at the channel, to fill the channel, wherein the ink has a viscosity, at screen printing temperature, less than that of a reference ink and low enough to improve, relative to the referenc ink, ink flow within the channel, and

ii. covering the filled channel with a second green tape, and

thereafter firing the green tapes and ink to remove organic materials in the green tapes and ink and densify the green tape,

wherein the reference ink is, by weight, 82.4% silver flake #15, 16.5% resin solution (which is 7.5% ethyl cellulose N14, 3.8% ethyl cellulose N300, 35.5% dodecanol, 53.2% butyl carbitol) and 1.1% of a 1:1 mixture of lecithin and terpeneol.

13. **(Previously Presented)** The method of claim 12, wherein embossing is conducted with tools heated to 115 to 200°F.

14. **(Previously Presented)** The method of claim 13, wherein embossing is conducted using a pressure of 1200 to 2400 psi.

15. **(Previously Amended)** The method of claim 12, wherein the embossed channel is filled with conductive ink.

16. **(Previously Presented)** The method of claim 15, wherein the conductive ink includes silver powder and an organic vehicle to provide a viscosity of about 30 poise.

17. **(Previously Presented)** The method of claim 12, wherein the embossed channel is filled with a resistor ink.

18. **(Previously Presented)** The method of claim 12, wherein the embossed channel is filled with a capacitor ink.

19. **(Previously Presented)** The method of claim 18, wherein the capacitor ink includes lead magnesium niobate.

20. **(Previously Presented)** The method of claim 18, wherein the capacitor ink includes barium titanate.

21. **(Previously Presented)** The method of claim 12, wherein more than one screen printing step is used to fill the channel.

22. **(Currently Amended)** A method of forming transmission lines and openings for buried passive components in green tapes comprising
embossing a channel directly on the surface of a green tape using heat and pressure sufficient to transfer the pattern from the embossing tool to the green tape,

screen printing conductive ink into the channel and covering by the steps consisting essentially of:

- i. screen printing a suitable said ink into the channel, and directly onto the surface of the green tape at the channel, to fill the channel, wherein the ink has a viscosity, at screen printing temperature, less than that of a reference ink and low enough to improve, relative to the referenc ink, ink flow within the channel, and
 - ii. covering the filled channel with a second green tape,
- covering the filled channel with a second green tape,
- thereafter aligning and laminating the green tapes onto a metal support coated with a low melt temperature glass, and
- firing the laminated green tapes to remove organic materials in the green tapes and ink and densify the green tape,
- wherein the reference ink is, by weight, 82.4% silver flake #15, 16.5% resin solution (which is 7.5% ethyl cellulose N14, 3.8% ethyl cellulose N300, 35.5% dodecanol, 53.2% butyl carbitol) and 1.1% of a 1:1 mixture of lecithin and terpineol.

23. **(Previously Presented)** The method of claim 22, wherein embossing is conducted with tools heated to 115 to 200°F.

24. **(Previously Presented)** The method of claim 23, wherein embossing is conducted using a pressure of 1200 to 2400 psi.

25. **(Previously Presented)** The method of claim 22, wherein the embossed channel is filled with conductive ink.

26. **(Previously Presented)** The method of claim 25, wherein the conductive ink includes silver powder and an organic vehicle to provide a viscosity of about 30 poise.

27. **(Previously Presented)** The method of claim 22, wherein the embossed channel is filled with a resistor ink.

28. **(Previously Presented)** The method of claim 22, wherein the embossed channel is filled with a capacitor ink.

29. **(Previously Presented)** The method of claim 28, wherein the capacitor ink includes lead magnesium niobate.

30. **(Previously Presented)** The method of claim 28, wherein the capacitor ink includes barium titanate.

31. **(Previously Presented)** The method of claim 22, wherein more than one screen printing step is used to fill the channel.

32. **(New)** The method of claim 12, wherein the channel has a width of 25-50 microns, with an accuracy of ± 2 microns.

33. **(New)** The method of claim 22, wherein the channel has a width of 25-50 microns, with an accuracy of ± 2 microns.